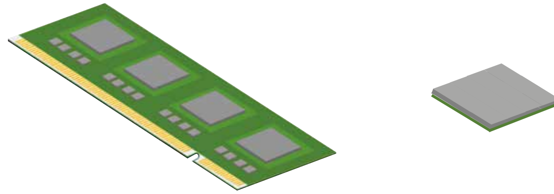
PBGA

Plastic Ball Grid Array

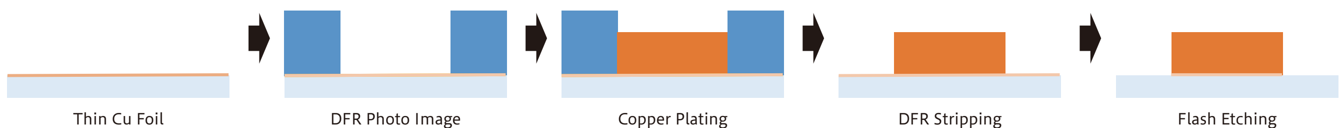
用途 Application

- メモリ、RFパターン
  Memory, Radio-Frequency pattern
- SiP
  Systen in package



工法 Construction method

MSAP
Modified Semi Additive Process



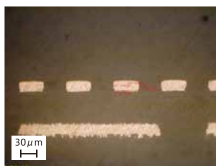
特長 Features

高精細パターン形成
High definition pattern formation

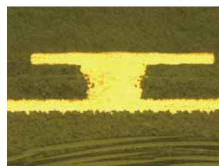
パターン幅ばらつき低減
Pattern width variation reduction

高精細パターン形成 High definition pattern formation

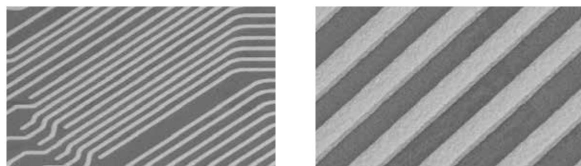
L/S=30/30
(Cross section)



LVH(φ100)
(Cross section)



L/S=25/25

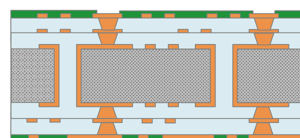


パターン幅ばらつき低減 Pattern width variation reduction

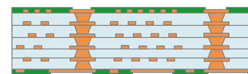
マイクロビア
Micro Via

パターン形成(MSAP法)
Pattern(MSAP)

薄板対応 Compatible with thinner PCB thickness



従来
コア:60～100μm
PP :40～60μm
Cu :約15～20μm
(図の例では約415μm)



コアレス
コア:なし
PP :15～20μm
Cu :約5～8μm
(図の例では約180μm)

コアレス工法との組み合わせにより薄板対応可
Compatible with thinner PCB thickness by Coreless process